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IFIP was founded in 1960 under the auspices of UNESCO, following the First World Computer Congress held in Paris the previous year. An umbrella organization for societies working in information processing, IFIP's aim is two-fold: to support information processing within its member countries and to encourage technology transfer to developing nations. As its mission statement clearly states,

IFIP's mission is to be the leading, truly international, apolitical organization which encourages and assists in the development, exploitation and application of information technology for the benefit of all people.

IFIP is a non-profitmaking organization, run almost solely by 2500 volunteers. It operates through a number of technical committees, which organize events and publications. IFIP's events range from an international congress to local seminars, but the most important are:

- The IFIP World Computer Congress, held every second year;
- Open conferences;
- Working conferences.

The flagship event is the IFIP World Computer Congress, at which both invited and contributed papers are presented. Contributed papers are rigorously refereed and the rejection rate is high.

As with the Congress, participation in the open conferences is open to all and papers may be invited or submitted. Again, submitted papers are stringently refereed.

The working conferences are structured differently. They are usually run by a working group and attendance is small and by invitation only. Their purpose is to create an atmosphere conducive to innovation and development. Refereeing is also rigorous and papers are subjected to extensive group discussion.

Publications arising from IFIP events vary. The papers presented at the IFIP World Computer Congress and at open conferences are published as conference proceedings, while the results of the working conferences are often published as collections of selected and edited papers.

Any national society whose primary activity is about information processing may apply to become a full member of IFIP, although full membership is restricted to one society per country. Full members are entitled to vote at the annual General Assembly, National societies preferring a less committed involvement may apply for associate or corresponding membership. Associate members enjoy the same benefits as full members, but without voting rights. Corresponding members are not represented in IFIP bodies. Affiliated membership is open to non-national societies, and individual and honorary membership schemes are also offered.

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Luc Claesen · Maria-Teresa Sanz-Pascual
Ricardo Reis · Arturo Sarmiento-Reyes (Eds.)

VLSI-SoC: Internet of Things Foundations

22nd IFIP WG 10.5/IEEE International Conference
on Very Large Scale Integration, VLSI-SoC 2014
Playa del Carmen, Mexico, October 6–8, 2014
Revised and Extended Selected Papers

 Springer

Editors

Luc Claesen
Hasselt University
Diepenbeek
Belgium

Maria-Teresa Sanz-Pascual
Electronics Department
INAOE
Tonantzintla, Puebla
Mexico

Ricardo Reis
Federal University of Rio Grande do Sul
Porto Alegre, Rio Grande do Sul
Brazil

Arturo Sarmiento-Reyes
Electronics Department
INAOE
Tonantzintla, Puebla
Mexico

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Preface

This book contains extended and revised versions of the highest-quality papers that were presented during the 22nd edition of the IFIP/IEEE WG10.5 International Conference on Very Large Scale Integration (VLSI-SoC), a global System-on-Chip Design and CAD conference. The 22nd conference was held at Iberostar Hotel in Playa del Carmen, Mexico (October 6–8, 2014). Previous conferences have taken place in Edinburgh, Scotland (1981); Trondheim, Norway (1983); Tokyo, Japan (1985); Vancouver, Canada (1987); Munich, Germany (1989); Edinburgh, Scotland (1991); Grenoble, France (1993); Chiba, Japan (1995); Gramado, Brazil (1997); Lisbon, Portugal (1997); Montpellier, France (2001); Darmstadt, Germany (2003); Perth, Australia (2005); Nice, France (2006); Atlanta, USA (2007); Rhodes, Greece (2008); Florianopolis, Brazil (2009); Madrid, Spain (2010); Kowloon, Hong Kong (2011), Santa Cruz, USA (2012), and Istanbul, Turkey (2013).

The purpose of this conference, which was sponsored by IFIP TC 10 Working Group 10.5, the IEEE Council on Electronic Design Automation (CEDA), and by IEEE Circuits and Systems Society, with the In-Cooperation of ACM SIGDA, was to provide a forum for the exchange of ideas and presentation of industrial and academic research results in the field of microelectronics design. The current trend toward increasing chip integration and technology process advancements has brought new challenges both at the physical and system design levels, as well as in the test of these systems. VLSI-SoC conferences aim to address these exciting new issues.

The quality of submissions (103 regular papers from 18 countries, excluding PhD Forum and special sessions) made the selection processes a very difficult one. Finally, 33 were accepted as full papers and 11 as posters. Out of the 33 full papers presented at the conference, 12 papers were chosen by a selection committee to have an extended and revised version included in this book. The selection process of these papers considered the evaluation scores during the review process as well as the review forms provided by members of the Technical Program Committee and session chairs as a result of the presentations.

The chapters of this book have authors from China, Denmark, France, Germany, Hong Kong, Italy, Ireland, Korea, The Netherlands, Switzerland, and USA. The Technical Program Committee comprised 112 members from 28 countries.

VLSI-SoC 2014 was the culmination of the work of many dedicated volunteers: paper authors, reviewers, session chairs, invited speakers, and various committee chairs. We thank them all for their contribution. Special thanks to Prof. Roberto Murphy for his invaluable help in the cumbersome tasks of local organization, finances, and registration.

This book is intended for the VLSI community, mainly those who did not have the chance to attend the conference. We hope you will enjoy reading this book and that you will find it useful in your professional life and for the development of the VLSI community as a whole.

August 2015

Luc Claesen
Maria-Teresa Sanz-Pascual
Ricardo Reis
Arturo Sarmiento-Reyes

Organization

The IFIP/IEEE International Conference on Very Large Scale Integration-System-on-Chip (VLSI-SoC) 2014 took place during October 6–8, 2014, in the Iberostar, Playa del Carmen, Mexico. VLSI-SoC 2014 was the 22nd in a series of international conferences, sponsored by IFIP TC 10 Working Group 10.5 (VLSI), IEEE CEDA, and ACM SIGDA.

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